**Product data sheet** 

## 1. General description

Silicon Carbide Schottky diode designed for high frequency switched mode power supplies in a TO252 (DPAK) plastic package.

#### 2. Features and benefits

- · Highly stable switching performance
- High forward surge capability I<sub>FSM</sub>
- · Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

## 3. Applications

- Power factor correction
- Telecom/Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED/OLED TV
- Motor Drives

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>RRM</sub>	repetitive peak reverse voltage		-	-	650	V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5 ; T <sub>mb</sub> ≤ 125 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3; Fig. 4	-	-	6	A
Tj	junction temperature		-	-	175	°C
Static charac	teristics					
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 6 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	1.5	1.7	V
		I <sub>F</sub> = 6 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	1.8	2.1	V
Dynamic cha	racteristics					
Q <sub>r</sub>	recovered charge	$I_F = 6 \text{ A}; dI_F/dt = 500 \text{ A/}\mu\text{s}; V_R = 400 \text{ V};$ $T_j = 25 \text{ °C}; Fig. 7$	-	10	-	nC

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected	mb	K — A
2	K	cathode[1]		001aaa020
3	Α	anode		
mb	К	mounting base; connected to cathode	DPAK (TO252NS)	

<sup>[1]</sup> It is not possible to connect to pin 2 of the TO252 package.

# **6. Ordering information**

### **Table 3. Ordering information**

Type number	Package						
	Name	Description	Version				
NXPSC06650D	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	TO252NS				

# 7. Limiting values

## **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	650	V
$V_{RWM}$	crest working reverse voltage		-	650	V
$V_R$	reverse voltage	DC	-	650	V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5 ; T <sub>mb</sub> ≤ 125 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3; Fig. 4	-	6	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5 ; t <sub>p</sub> = 25 µs; square-wave pulse	-	12	Α
I <sub>FSM</sub>	non-repetitive peak	t <sub>p</sub> = 10 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse	-	36	Α
	forward current	$t_p$ = 10 $\mu$ s; $T_{j(init)}$ = 25 °C; square-wave pulse	-	310	А
T <sub>stg</sub>	storage temperature		-55	175	°C
T <sub>j</sub>	junction temperature		-	175	°C

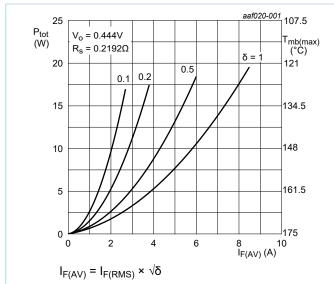


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

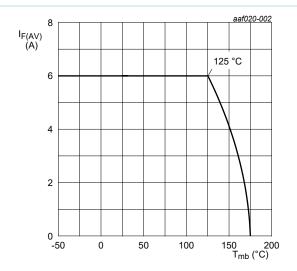


Fig. 2. Forward current as a function of mounting base temperature; maximum values

WeEn Semiconductors NXPSC06650D

#### Silicon Carbide Diode

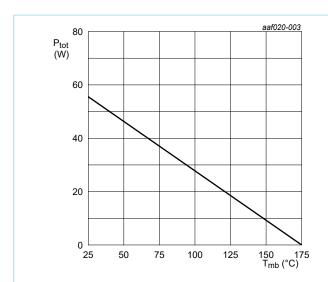


Fig. 3. Total power dissipation as a function of mounting base temperature

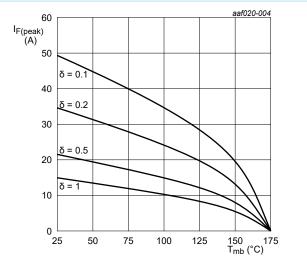


Fig. 4. Current derating as a function of mounting base temperature

## 8. Thermal characteristics

**Table 5. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	<u>Fig. 5</u>	-	-	2.7	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	Device mounted on an FR4 Printed- Circuit Board	-	50	-	K/W

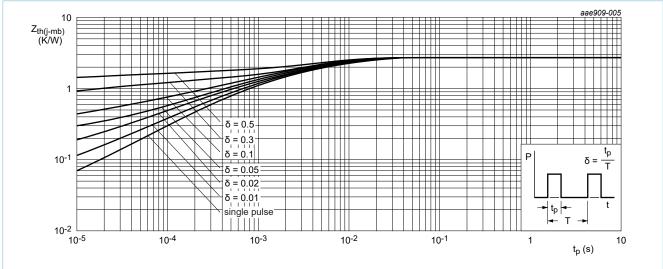
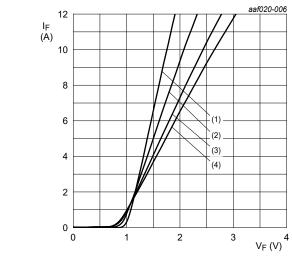


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 9. Characteristics

#### **Table 6. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	cteristics					,
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 6 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	1.5	1.7	V
		I <sub>F</sub> = 6 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	1.8	2.1	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C	_	-	200	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 150 °C	_	-	640	μA
Dynamic ch	aracteristics					,
Q <sub>r</sub>	recovered charge	$I_F = 6 \text{ A}; dI_F/dt = 500 \text{ A/}\mu\text{s}; V_R = 400 \text{ V};$ $T_j = 25 \text{ °C}; Fig. 7$	-	10	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C	-	190	-	pF
		$f = 1 \text{ MHz}; V_R = 300 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	23	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C	-	19	-	pF



(1)  $T_j$  = 25 °C; typical values (2)  $T_j$  = 100 °C; typical values (3)  $T_j$  = 150 °C; typical values (4)  $T_j$  = 175 °C; typical values



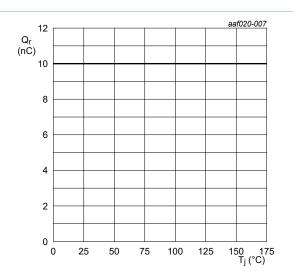


Fig. 7. Recovered charge as a function of junction temperature

## 10. Package outline

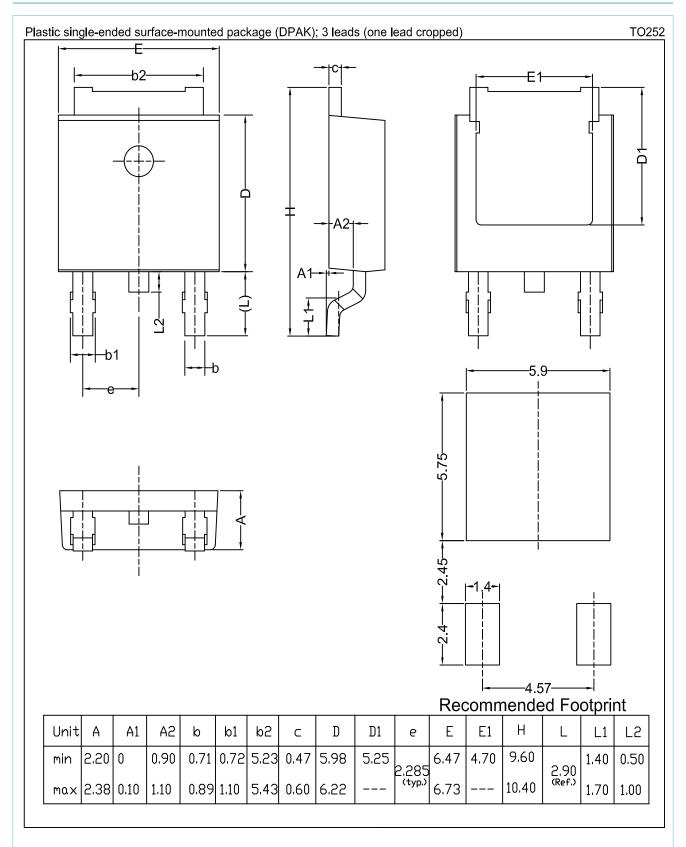


Fig. 8. Package outline DPAK (TO252NS)

7 / 10

# 11. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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## 12. Contents

1.	General description	1
2.	Features and benefits	. 1
3.	Applications	. 1
4.	Quick reference data	1
5.	Pinning information	2
6.	Ordering information	2
7.	Limiting values	. 3
8.	Thermal characteristics	. 5
9.	Characteristics	. 6
10.	Package outline	. 7
11.	. Legal information	. 8

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